

Initial Product/Process Change Notification Document #:IPCN23735XA

Issue Date:29 Nov 2021

Title of Change:	Qualification of ASE foundry for WLCSP and onsemi Cebu site for probe and assembly. Carrier tape dimensions are changed and include corner relief.		
Proposed First Ship date:	05 Apr 2022 or earlier if approved by customer		
Contact Information:	Contact your local onsemi Sales Office or Jeremy.Ferris@onsemi.com		
PCN Samples Contact:	Contact your local onsemi Sales Office or < PCN.samples@onsemi.com . Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.		
Type of Notification:	This is an Initial Product/Process Change Notification (IPCN) sent to customers. An IPCN is an advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan. The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCN). This IPCN notification will be followed by a Final Product/Process Change Notification (FPCN) at least 90 days prior to implementation of the change. In case of questions, contact < PCN.Support@onsemi.com >		
Marking of Parts/ Traceability of Change:	Changed Parts will be identified by a new plant code.		
Change Category:	Assembly Change, Tes	Assembly Change, Test Change, Bump Site Change	
Change Sub-Category(s):	Shipping/Packaging/Ma	Shipping/Packaging/Marking, Manufacturing Site Transfer	
Sites Affected:			
onsemi Sites		External Foundry/Subcon Sites	
onsemi, Niigata Japan		ASEKH, Taiwan (Kaohsiung)	
onsemi, Seremban Malaysia			
onsemi Cebu, Philippines			

Description and Purpose:

This Product Change Notification is to announce the Qualification of ASE foundry for WLCSP and onsemi, Cebu site for probe and assembly. Carrier tape dimensions are changed and include corner relief.

	Before Change Description	After Change Description	
WLCSP Bump/Backgrind/Backside Coating location	onsemi, Niigata Japan	Subcontractor ASEKH, Kaohsiung Taiwan	
Final Test and Assembly Site	onsemi, Seremban Malaysia	onsemi, Cebu Philippines	
Under Bump Metal Composition	Ni/Au	Cu	
Backside Coating	ADWILLLC2821(LINTEC)	ADWILL LC2850H (LINTEC)	
	Ao = 1.07 +/-0.05mm	Ao = 1.20+/-0.05mm	
Pocket Dimension	Bo = 1.42 +/-0.05mm	Bo = 1.45+/-0.05mm	
	Ko = 0.74 +/-0.05mm	Ko = 0.69+/-0.05mm	
Pocket Design No corner relief		With Corner relief	

	From	То
Product marking change	onsemi Malaysia: R	onsemi, Cebu Philippines: D

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Qualification Plan:

QV DEVICE NAME: FPF2498BUCX

RMS:74804

PACKAGE: WLCSP

Test	Specification	Condition	Interval
TC	JESD22-A104	Ta= -40°C to +125°C	850 cyc
HAST	JESD22-A110	130°C, 85% RH, 18.8psig, bias	96 hrs
uHAST	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs
PC	J-STD-020 JESD-A113	MSL 1 @260 °C	
SD	JSTD002	Ta = 245C, 5 sec	
PD	Per outline	Per outline drawing	20 units

List of Affected Parts:

Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the **PCN Customized Portal**.

Part Number	Qualification Vehicle
FPF2498BUCX	FPF2498BUCX

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